



SD-101-ACP11
W16.50xD27.70xH2.80

PIN 数(Number of contacts) : 9+2PIN

耐电压(Withstand voltage) : 250V AC for 1 min

操作方式(Operation mode): 抽拉式/PUSH PULL

操作寿命(Operation life): 5,000 Cycles Min

温度范围(Operating temp): -40°C TO +80°C

焊接温度(Welding temperature): 260±5° 5s

额定负荷(Rated load): 0.5A PERP IN.

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance): 100mΩ max.

包装方式(Packaging method): 吸塑盘装/Tray

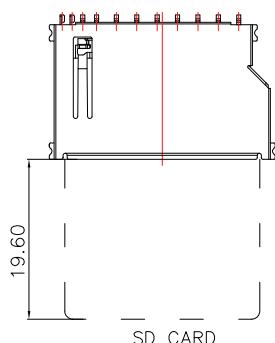
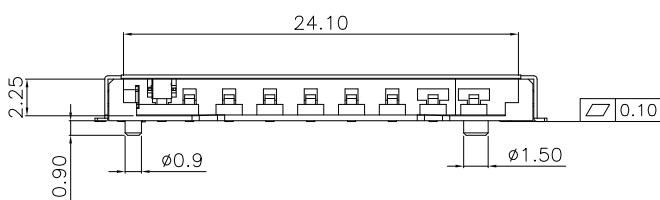
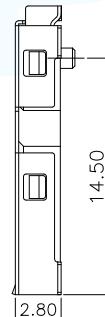
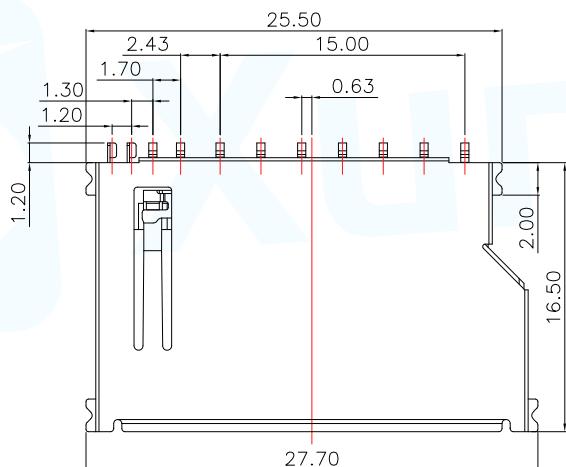
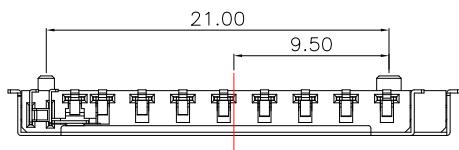
绝缘电阻(Insulation resistance): 1000MΩ min.

最小包装(Minimum packing): 50/PCS

外形尺寸(UNIT:MM) / Size Chart

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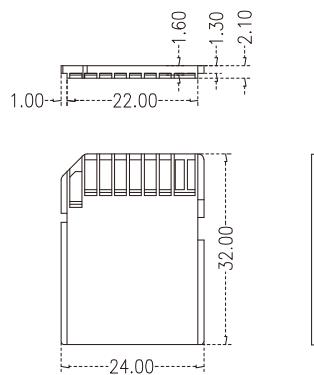
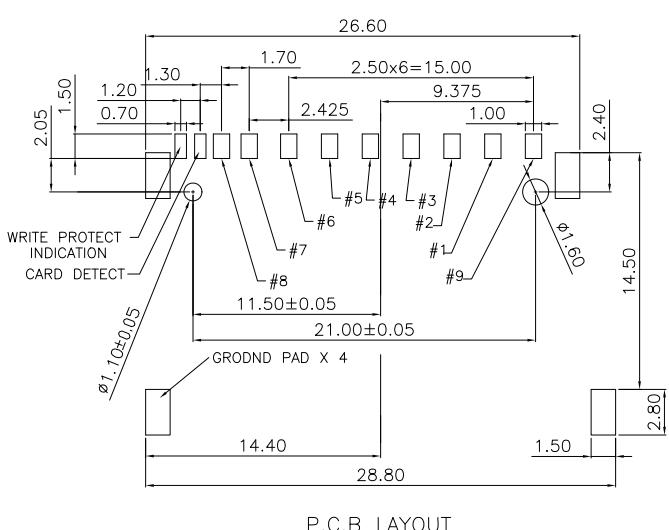
更多资料请参考技术选型档!



NOTES

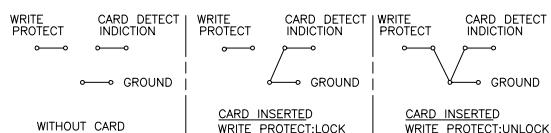
1. All Dimensions are in Millimeters.
2. Operation voltage: 100 VAC max.
3. Current rating: 1 Amps max.
4. Contact resistance: 100m ohms max.
5. Insulation resistance: 1000M ohms min. 500 VDC
6. Dielectric withstanding voltage: 500 VAC / 1 minute
7. Operating Temperature: -20°C to +60°C
8. Storage Temperature: -40°C to +70°C
9. Material see table.
10. Total Mating Force: 40N(MAX) at 25 mm/minute
11. Total Unmating Force: 2N(MIN) at 25 mm/minute
12. Single Pin Retention Force: 3.0N(MIN) at 25 mm/minute

SD CARD



引脚定义/Pin Definition

PIN#	NAME	DESCRIPTION
1	DAT3	DATA LINE BIT3
2	CMD	COMMAND/RESPONSE
3	VSS1	SUPPLY VOLTAGE GROUND
4	VDD1	SUPPLY VOLTAGE
5	CLK	CLOCK
6	VSS2	SUPPLY VOLTAGE GROUND
7	DAT0	DATA LINE BIT0
8	DAT1	DATA LINE BIT1
9	DAT2	DATA LINE BIT2
10	CD	CARD DETECT
11	WP	WRITE PROTECT

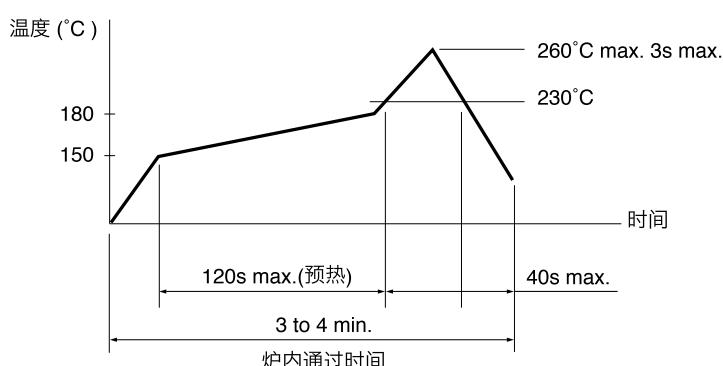


Circuit Diagram for Detect Switch

焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
温度分布/Temperature distribution



手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2 的 CA(K) 或 CC(T) 测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。